Low VF Glass Passivated Bridge Rectifiers
玻璃钝化低功耗整流桥

Reverse Voltage - 800 Volts
反向电压 800V
Forward Current - 15 Amperes
正向电流 15A

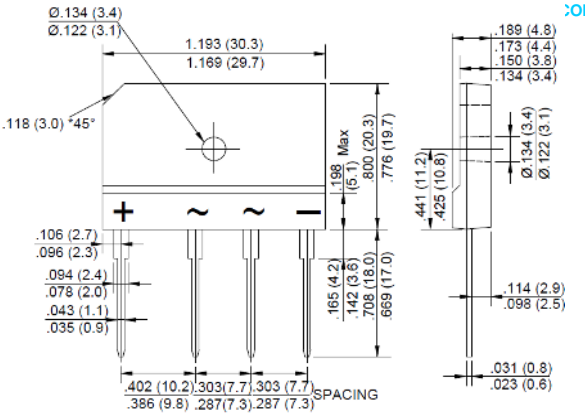
Features 特征
- Glass passivated chip 玻璃钝化芯片
- Low forward voltage drop 正向压降低
- Ideal for printed circuit board 适用于印刷电路板中
- High surge current capability 高的浪涌能力

Mechanical Data 外观信息
- Polarity: Symbol marked on body 极性：标志在产品的本体上
- Mounting position: Any 安装位置：任何位置

Applications 应用
- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.
  一般应用于交流/直流桥式全波整流，如：开关电源，照明镇流器、适配器等。

GBJ

RoHS COMPLIANT



Package Outline Dimensions in Inches (Millimeters)
封装外观尺寸单位英寸（毫米）

Maximum Ratings and Electrical Characteristics 最大额定值及电气特性

Rating at 25℃ ambient temperature unless otherwise specified. 环境温度25℃，除非特别说明。
Single phase, half wave, 60Hz, resistive or inductive load. 单相半波， 60Hz， 阻性或感性负载。
For capacitive load, derate current by 20%. 对于电容性负载，降低20%的额定电流。

Characteristics 特性	Symbol 符号	GBJ1508F	Unit 单位
Maximum Repetitive Peak Reverse Voltage 最大重复峰值反向电压	V_{RRM}	800	V
Maximum RMS Voltage 最大有效反向电压	V_{RMS}	560	V
Maximum DC Blocking Voltage 最大直流阻断电压	V_{DC}	800	V
Maximum Average Forward Rectified Current (with heatsink Note 2) 最大正向平均整流电流 @ T_C=100℃ (without heatsink)	$I_{(AV)}$	15.0 3.7	A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method) 8.3mS单一正弦半波叠加在额定负载上的浪涌能力（JEDEC方法）	I_{FSM}	240	A
I^2t Rating for Fusing (t<8.3mS) 熔断额定值 （t＜8.3mS)	I^2t	239	A^2s
Peak Forward Voltage per Diode at 7.5A DC 单个二极管在7. 5A电流下的正向峰值电压	V_F	0.92	V
Maximum DC Reverse Current at Rated @T_J=25℃ DC Bolcking Voltage per Diode @T_J=125℃ 单个二极管在额定直流电压下的最大反向直流电流	I_R	5.0 500	μA
Typical Junction Capacitance per Diode (Note1) 典型结电容（备注1）	C_J	60	pF
Typical Thermal Resistance to Ambient (Note2) 结到环境的典型热阻值（备注2） Typical Thermal Resistance to case (Note2) 结到壳的典型热阻值（备注2） Typical Thermal Resistance to lead (Note2) 结到引线的典型热阻值（备注2）	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	4.5 0.8 1.5	℃/W
Operating Junction Temperature Range 结温工作范围	T_J	-55 to +150	℃
Storage Temperature Range 储存温度范围	T_{STG}	-55 to +150	℃

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC. 在 1.0MHz 下和反向电压为 4.0V DC下测试。
2.Device mounted on 300mm*300mm*1.6mm Cu plate heatsink. 安装在 300mm*300mm*1.6mm Cu 的散热片上。
3.The typical data above is for reference only 典型值仅供参考.

Fig. 1 - Forward Current Derating Curve
图1 正向电流降额曲线

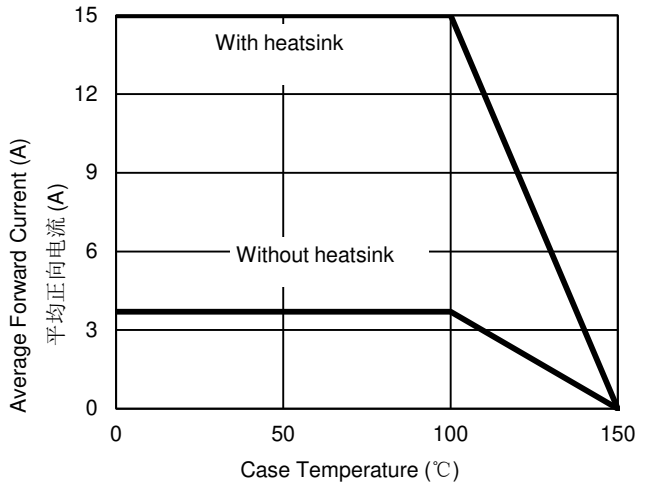


Fig. 2 - Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

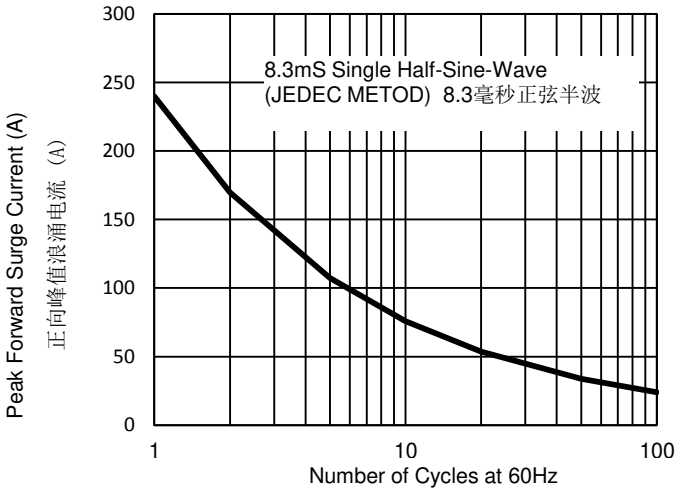


Fig. 3 - Typical Reverse Characteristics
图3 典型的反向特性

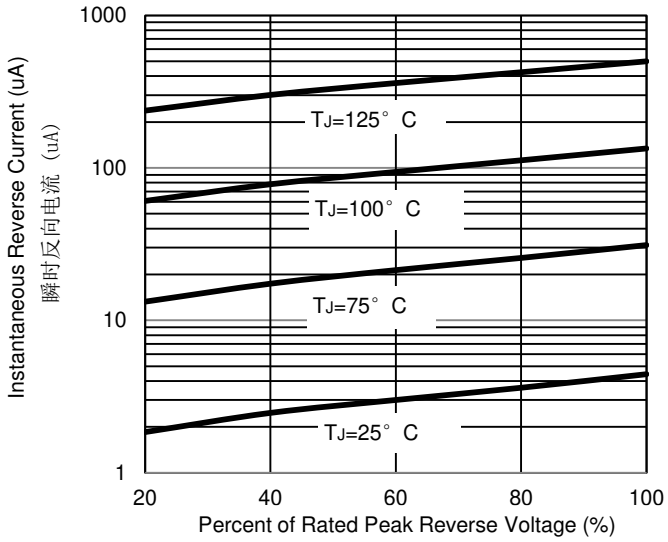


Fig. 4 - Typical Forward Characteristics
图4 典型的正向特性

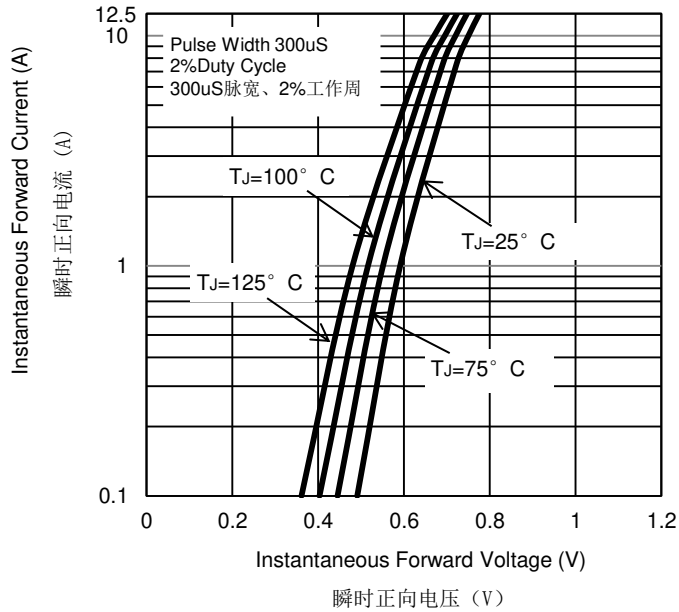
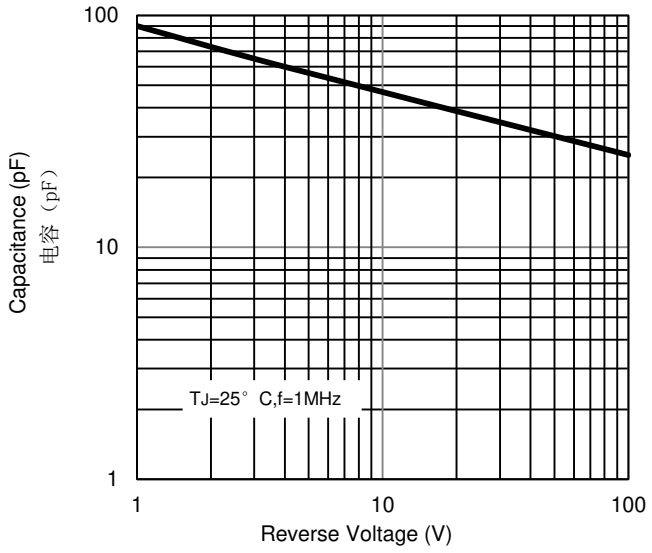


Fig. 5 - Typical Junction Capacitance
图5 典型的结电容



The curve above is for reference only. 曲线图仅供参考。

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